

### IN THE CLAIMS

Please amend claims 1, 3 and 4, and add claims 47-50, as set forth below. The following is a listing of the claims and status indicators in accordance with 37 C.F.R. §1.121. This listing replaces all prior listings of claims.

1. (Currently Amended) A package comprising:
  - a flexible substrate comprising a polymeric transparent film;
  - an organic electronic device coupled to the transparent film;
  - a sealant coupled to the flexible substrate and disposed about the perimeter of the organic electronic device; and
  - a superstrate coupled directly to the sealant and disposed proximate to the organic electronic device, wherein the superstrate comprises a periphery adapted to wrap around the edges of the package.
2. (Previously Presented) The package, as set forth in claim 1, wherein the flexible substrate comprises a barrier coating.
3. (Currently Amended) The package, as set forth in claim 1, wherein the flexible substrate is a composite substrate comprising:
  - a first protective layer configured to resist abrasion;
  - a polymeric transparent film coupled to the first protective layer;
  - a barrier coating coupled to the transparent film; and
  - a second protective layer coupled to the barrier coating and configured to protect the transparent film from chemical attack<sub>[[h]]</sub> during fabrication.
4. (Currently Amended) The package, as set forth in claim 1, wherein the flexible substrate is a composite substrate comprising:
  - a first protective layer configured to resist abrasion;
  - a first polymeric transparent film coupled to the first protective layer;
  - a first barrier coating coupled to the first transparent film;
  - a second barrier coating coupled to the first barrier coating via an adhesive layer;



a second polymeric transparent film coupled to the second barrier coating; and  
a second protective layer coupled to the barrier coating and configured to protect the transparent film from chemical attack during fabrication.

5. (Original) The package, as set forth in claim 1, comprising a barrier coating coupled between the flexible substrate and the organic electronic device.

6. (Original) The package, as set forth in claim 1, wherein the organic electronic device comprises an organic light emitting diode.

7. (Original) The package, as set forth in claim 1, wherein the organic electronic device comprises an organic photovoltaic device.

8. (Original) The package, as set forth in claim 1, wherein the sealant comprises an adhesive material having a low permeability.

9. (Original) The package, as set forth in claim 1, wherein the sealant comprises a thickness that is greater than a thickness of the organic electronic device.

10. (Original) The package, as set forth in claim 1, wherein the superstrate comprises a metal foil.

11. (Withdrawn) A package comprising:  
a flexible substrate comprising a polymeric transparent film;  
an organic electronic device coupled to the transparent film;  
a sealant coupled to the transparent film and disposed about the perimeter of the organic electronic device; and  
a superstrate coupled to the sealant and disposed proximate to the organic electronic device, wherein the superstrate comprises a periphery adapted to wrap around edges of the package such that



the periphery of the superstrate is coupled to a side of the flexible substrate opposite the organic electronic device.

12. (Withdrawn) The package, as set forth in claim 11, wherein the flexible substrate comprises the barrier coating.

13. (Withdrawn) The package, as set forth in claim 11, wherein the flexible substrate is a composite substrate comprising:

- a first protective layer configured to resist abrasion;
- a polymeric transparent film coupled to the first protective layer;
- a barrier coating coupled to the transparent film; and
- a second protective layer coupled to the barrier coating and configured to protect the transparent film from chemical attack during fabrication.

14. (Withdrawn) The package, as set forth in claim 11, wherein the flexible substrate is a composite substrate comprising:

- a first protective layer configured to resist abrasion;
- a first polymeric transparent film coupled to the first protective layer;
- a first barrier coating coupled to the first transparent film;
- a second barrier coating coupled to the first barrier coating via an adhesive layer;
- a second polymeric transparent film coupled to the second barrier coating; and
- a second protective layer coupled to the barrier coating and configured to protect the transparent film from chemical attack during fabrication.

15. (Withdrawn) The package, as set forth in claim 11, comprising a barrier coating coupled between the flexible substrate and the organic electronic device.

16. (Withdrawn) The package, as set forth in claim 11, wherein the organic electronic device comprises an organic light emitting diode.



17. (Withdrawn) The package, as set forth in claim 11, wherein the organic electronic device comprises an organic photovoltaic device.

18. (Withdrawn) The package, as set forth in claim 11, wherein the sealant comprises an adhesive material having a low permeability.

19. (Withdrawn) The package, as set forth in claim 11, wherein the sealant comprises a thickness that is greater than a thickness of the organic electronic device.

20. (Withdrawn) The package, as set forth in claim 11, wherein the superstrate comprises a metal foil.

21. (Withdrawn) The package, as set forth in claim 11, comprising a desiccant material disposed within pockets formed by wrapping the edges of the package with the superstrate.

22. (Withdrawn) A package comprising:  
a flexible substrate comprising a polymeric transparent film;  
an organic electronic device coupled to the transparent film;  
a sealant coupled to the transparent film and disposed about the  
perimeter of the organic electronic device;  
a superstrate coupled to the sealant and disposed proximate the organic  
electronic device; and  
an edge seal coupled to each of the flexible substrate and the superstrate  
and configured to hermetically seal peripheral edges of the  
package.

23. (Withdrawn) The package, as set forth in claim 22, wherein the flexible substrate comprises the barrier coating.

24. (Withdrawn) The package, as set forth in claim 22, wherein the flexible substrate is a composite substrate comprising:



a first protective layer configured to resist abrasion;  
a polymeric transparent film coupled to the first protective layer;  
a barrier coating coupled to the transparent film; and  
a second protective layer coupled to the barrier coating and configured to  
protect the transparent film from chemical attack during  
fabrication.

25. (Withdrawn) The package, as set forth in claim 22, wherein the flexible substrate is a composite substrate comprising:

a first protective layer configured to resist abrasion;  
a first polymeric transparent film coupled to the first protective layer;  
a first barrier coating coupled to the first transparent film;  
a second barrier coating coupled to the first barrier coating via an  
adhesive layer;  
a second polymeric transparent film coupled to the second barrier  
coating; and  
a second protective layer coupled to the barrier coating and configured to  
protect the transparent film from chemical attack during  
fabrication.

26. (Withdrawn) The package, as set forth in claim 22, comprising a barrier coating coupled between the flexible substrate and the organic electronic device.

27. (Withdrawn) The package, as set forth in claim 22, wherein the organic electronic device comprises an organic light emitting diode.

28. (Withdrawn) The package, as set forth in claim 22, wherein the organic electronic device comprises an organic photovoltaic device.

29. (Withdrawn) The package, as set forth in claim 22, wherein the sealant comprises an adhesive material having a low permeability.



30. (Withdrawn) The package, as set forth in claim 22, wherein the sealant comprises a thickness that is greater than a thickness of the organic electronic device.

31. (Withdrawn) The package, as set forth in claim 22, wherein the superstrate comprises a metal foil.

32. (Withdrawn) The package, as set forth in claim 22, comprising a desiccant material disposed within pockets formed by the edge seal.

33. (Withdrawn) The package, as set forth in claim 22, wherein the edge seal comprises a metal foil.

34 – 46. (Canceled)

47. (New) A package comprising:  
a flexible substrate comprising a polymeric transparent film;  
an organic electronic device coupled to the transparent film;  
a sealant coupled to the flexible substrate and disposed about the perimeter of the organic electronic device; and  
a superstrate coupled directly to the sealant and disposed proximate to the organic electronic device, wherein the superstrate comprises at least one layer larger than the flexible substrate and a periphery adapted to wrap around the edges of the package.

48. (New) The package, as set forth in claim 47, wherein the flexible substrate is a composite substrate comprising:  
a first protective layer configured to resist abrasion;  
a polymeric transparent film coupled to the first protective layer;  
a barrier coating coupled to the transparent film; and  
a second protective layer coupled to the barrier coating and configured to protect the transparent film from chemical attack during fabrication.



49. (New) The package, as set forth in claim 47, wherein the flexible substrate is a composite substrate comprising:

- a first protective layer configured to resist abrasion;
- a first polymeric transparent film coupled to the first protective layer;
- a first barrier coating coupled to the first transparent film;
- a second barrier coating coupled to the first barrier coating via an adhesive layer;
- a second polymeric transparent film coupled to the second barrier coating; and
- a second protective layer coupled to the barrier coating and configured to protect the transparent film from chemical attack during fabrication.

50. (New) The package, as set forth in claim 47, wherein the superstrate comprises a metal foil.